

DANA LYNN LANSIGAN

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EDUCATION

University of California, Berkeley — Berkeley, CA — GPA 3.952

May 2019

- ♦ Pursuing Bachelor of Science in Mechanical Engineering

Irvine High School — Irvine, CA — GPA 4.58

June 2015

- ♦ Ranked in top 9% of class of 400

TECHNICAL SKILLS

- ♦ Skilled in AutoCAD, SolidWorks
- ♦ Self-taught in HTML, CSS, jQuery
- ♦ Experienced in Matlab

COURSEWORK

- ♦ E 25 Visualization for Design, AutoCAD
- ♦ E 26 SolidWorks (planned)
- ♦ E 27 Intro to Manufacturing and Tolerancing
- ♦ E 7 Matlab
- ♦ ME C85 Solid Mechanics (planned)

LAB EXPERIENCE

Undergraduate Researcher

February 2016 - present

Design for Nanomanufacturing Lab, University of California Berkeley

- ♦ Prepared semiconductor chip samples and stamps using a spin coater and UV aligner
- ♦ Collected video data for nanoimprint lithography research using Matlab and Thorlabs components
- ♦ Communicated experiment results to researchers

Lab Assistant

Summer 2016

Wind Tunnel Lab, University of California Irvine

- ♦ Fabricated hot wire sensors with chemical lab equipment
- ♦ Operated wind tunnel to collect data for turbulence experiments
- ♦ Developed Matlab code for analyzing experiment data

ACTIVITIES

Empennage Co-Lead, Internal Affairs

September 2015 - present

Aero Design Society of Automotive Engineers (SAE)

- ♦ Modeled empennage designs with SolidWorks
- ♦ Employed woodworking skills to construct model airplane for competition
- ♦ Designed and coded professional team website
- ♦ Organized officer board meetings to discuss plane design and club logistics

Engineering Representative Intern

September 2015 - May 2016

Pilipino Association of Scientists, Architects, and Engineers (PASAE)

- ♦ Assisted in assembling monthly engineering newsletter for organization
- ♦ Facilitated academic and cultural workshops for high school students during Filipino Empowerment Day and Senior Weekend

PROJECTS

CalCase

May 2016

- ♦ Designed and manufactured a phone case that holds a credit card, an ID card, and a key ring
- ♦ Modeled with SolidWorks and 3D printed with Stratasys Objet printer
- ♦ Applied tolerances for desired fits derived from machinist's handbooks
- ♦ Worked with teammates to optimize design and manufacturing process

AWARDS & HONORS

UC Berkeley College of Engineering Dean's Honors List

Fall, Spring 2016

- ♦ Academic honor awarded to engineering students with a GPA in the top 10% of undergraduates in the College of Engineering